



US00D864882S

(12) **United States Design Patent**  
**Sakamoto**

(10) **Patent No.:** **US D864,882 S**  
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(54) **PART FOR SEMICONDUCTOR DEVICE**

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- (\*\*) Term: **15 Years**
- (21) Appl. No.: **29/641,834**
- (22) Filed: **Mar. 26, 2018**

(57) **CLAIM**

The ornamental design for a part for semiconductor device, as shown and described.

(30) **Foreign Application Priority Data**

Sep. 27, 2017 (JP) ..... 2017-021146

(51) **LOC (12) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**

USPC ..... D13/110, 182; 257/678, 684, 690, 691;  
361/679.01, 713, 728, 736, 760, 761, 772,  
361/775, 783, 820; 174/250, 253;  
438/15, 25, 26, 51, 55, 63, 64, 106  
CPC . H01L 21/00; H01L 2224/42; H01L 2224/43;  
H01L 2021/00; H01L 2021/02; H01L  
2021/04; H01L 21/4814; H01L 21/4846;  
H01L 21/4871; H01L 21/67144; H01L  
23/12; H01L 23/13; H01L 23/14; H01L  
23/147; H01L 2924/171; H01L  
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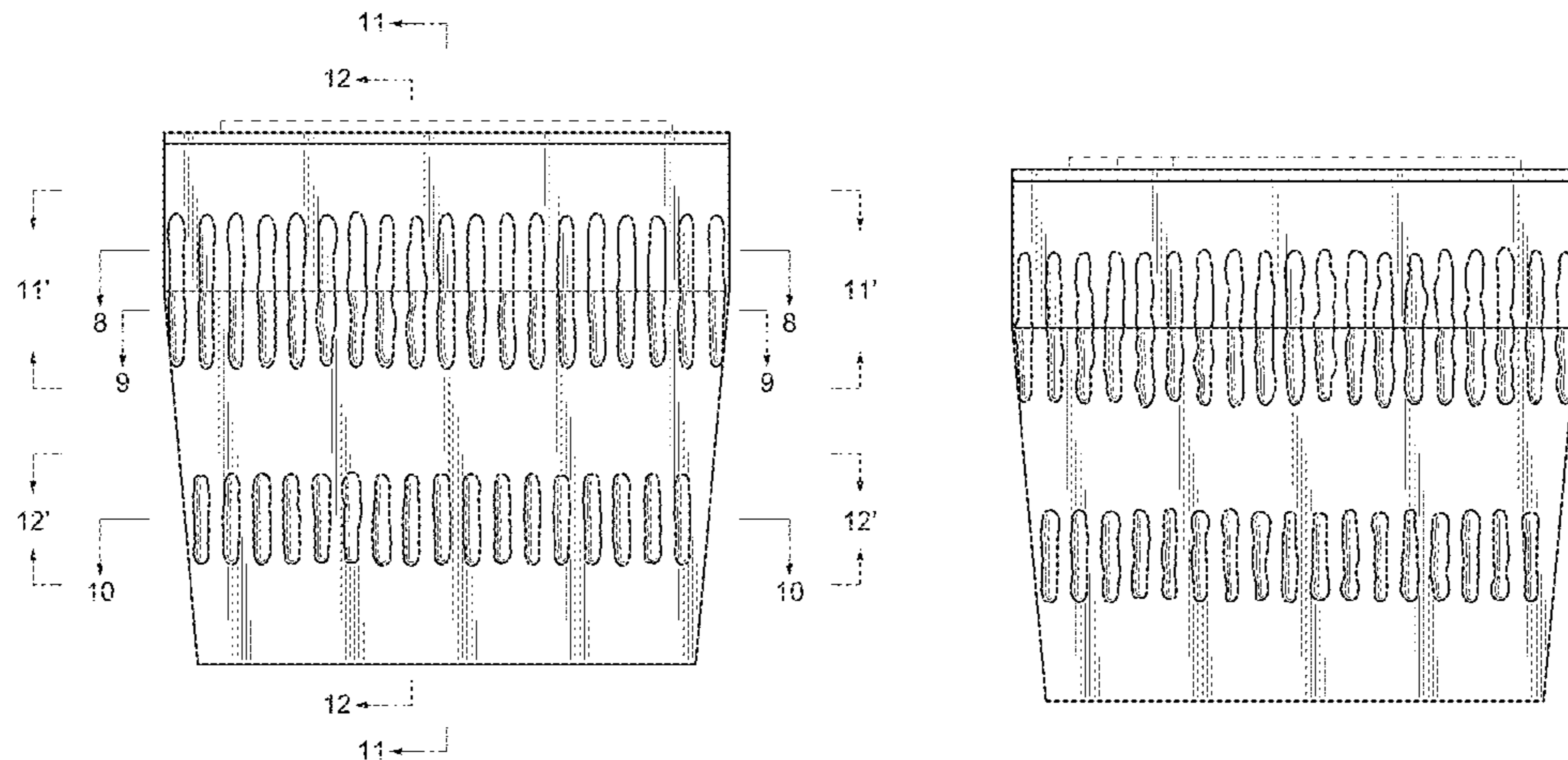
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**DESCRIPTION**

FIG. 1 is a front view of a part for semiconductor device showing my new design;  
FIG. 2 is a rear view thereof;  
FIG. 3 is a top plan view thereof;  
FIG. 4 is a bottom plan view thereof;  
FIG. 5 is a right side view thereof;  
FIG. 6 is a left side view thereof;  
FIG. 7 is a perspective view thereof;  
FIG. 8 is an enlarged cross-sectional view taken along line 8-8 in FIG. 1;  
FIG. 9 is an enlarged cross-sectional view taken along line 9-9 in FIG. 1;  
FIG. 10 is an enlarged cross-sectional view taken along line 10-10 in FIG. 1;  
FIG. 11 is an enlarged cross-sectional view of a portion labeled 11'-11' in FIG. 1 and a portion labeled 11"-11" in FIG. 5 taken along line 11-11 in FIG. 1; and,  
FIG. 12 is an enlarged cross-sectional view of a portion labeled 12'-12' in FIG. 1 and a portion labeled 12"-12" in FIG. 5 taken along line 12-12 in FIG. 1.  
The features shown in broken lines depict environmental subject matter only and form no part of the claimed design.

**1 Claim, 12 Drawing Sheets**



(58) **Field of Classification Search**

CPC ..... 2924/171151; H01L 2924/181; H01L  
2924/1811; H01L 2924/1815; H01L  
2924/19042; H01L 2224/08054; H01L  
23/58; H05B 41/14; H05K 1/142; H05K  
1/144; H05K 1/18; H05K 1/181; H05K  
1/182; H05K 1/026

See application file for complete search history.

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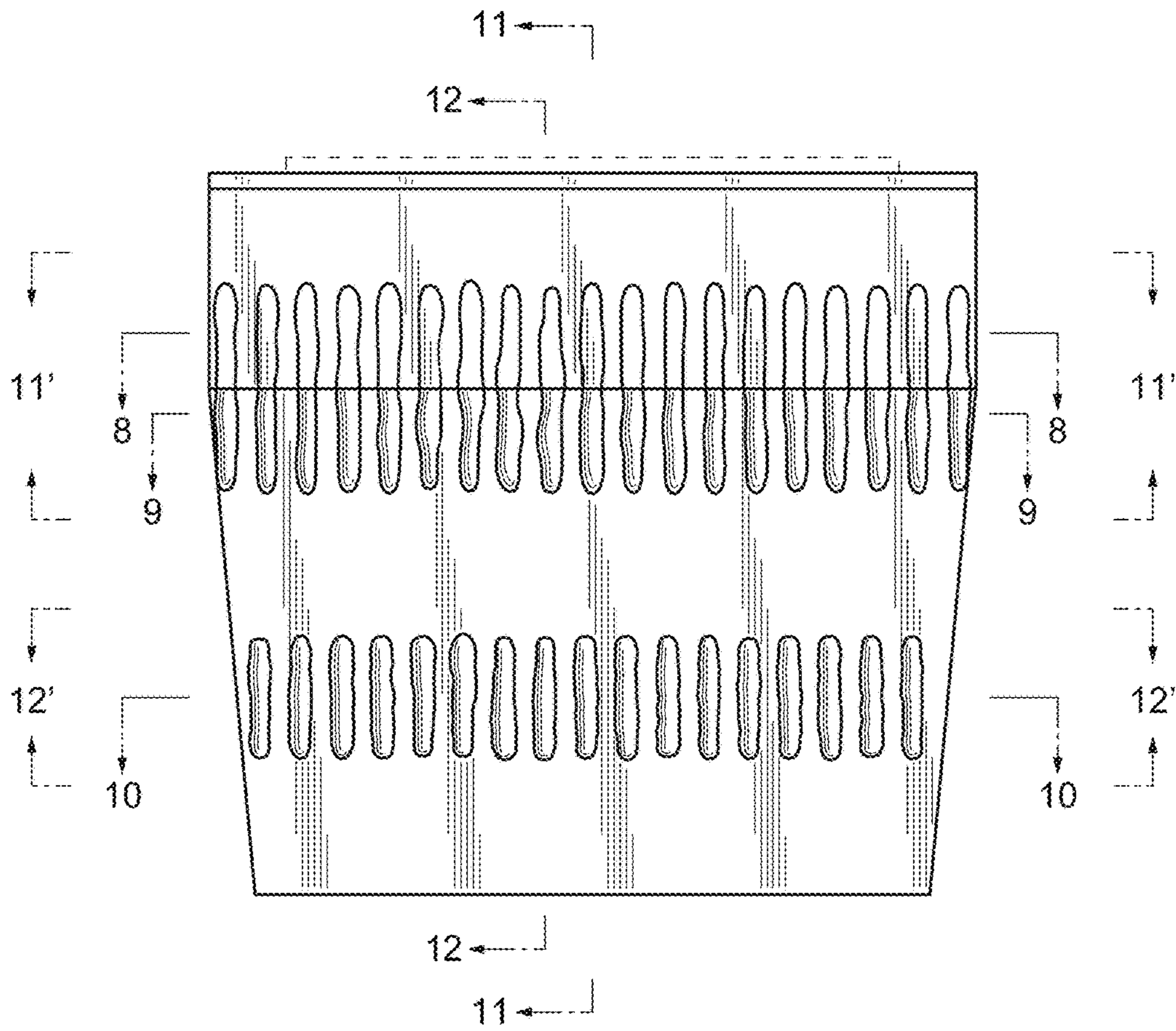


FIG. 1

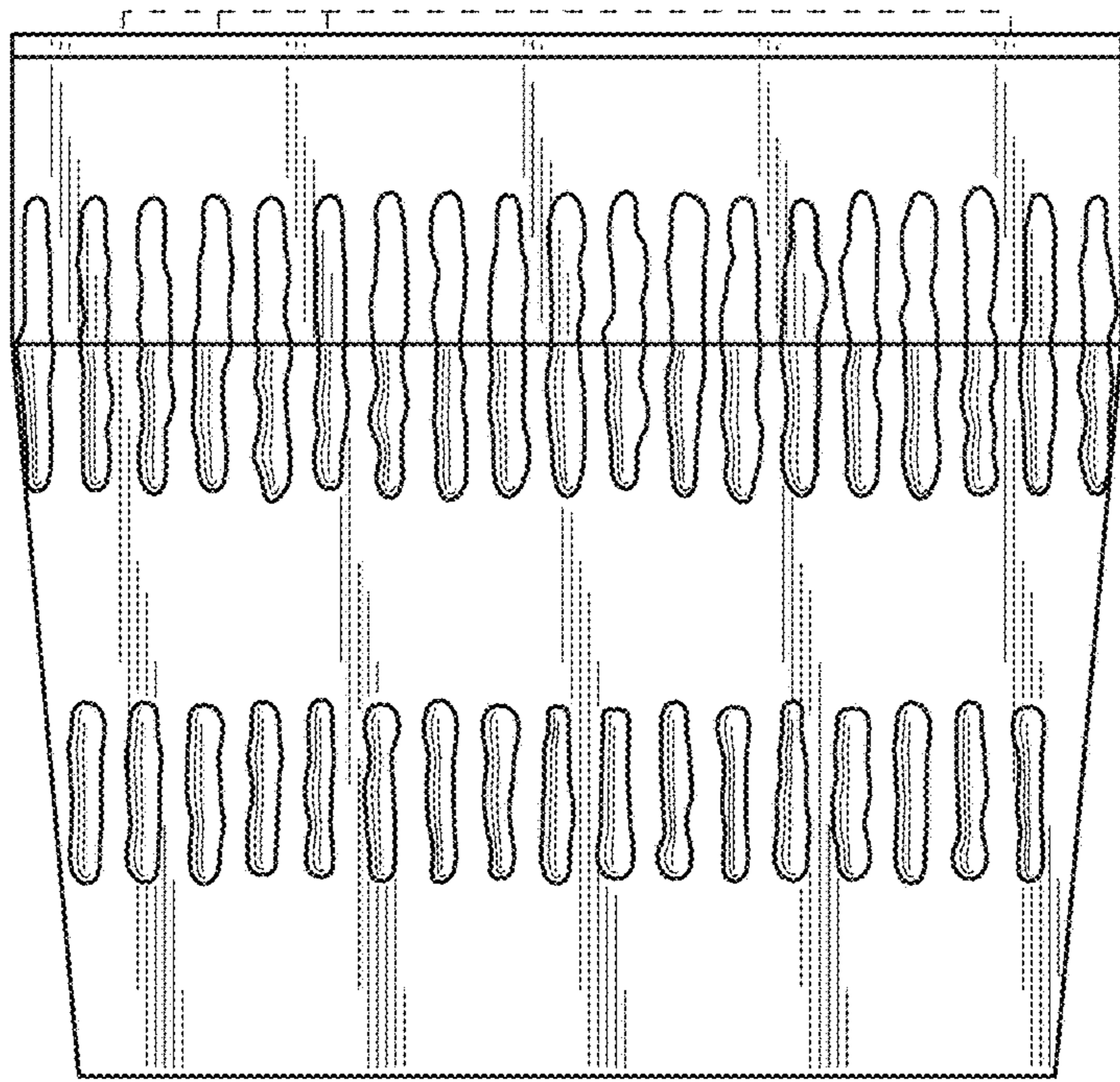


FIG. 2

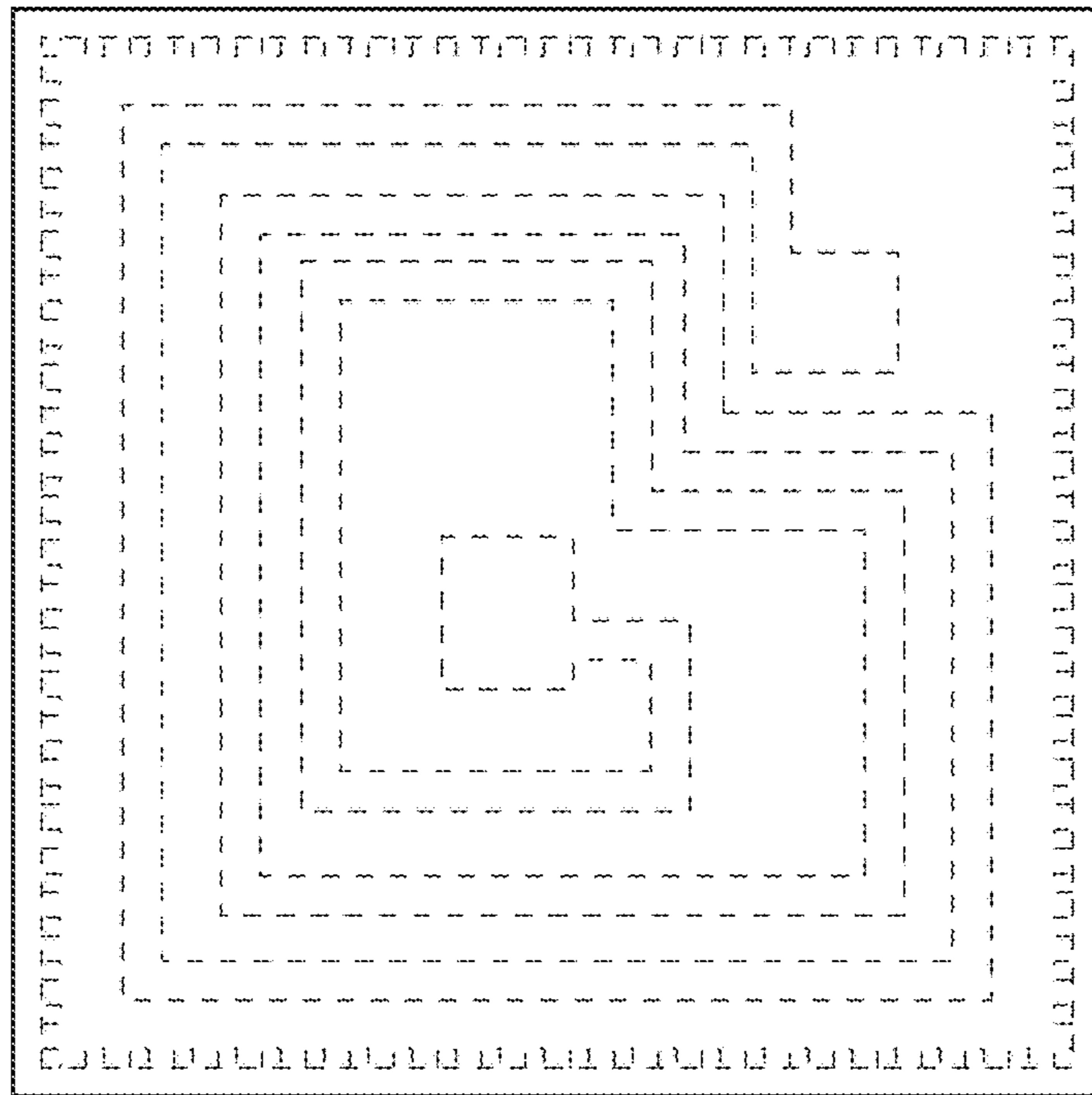


FIG. 3

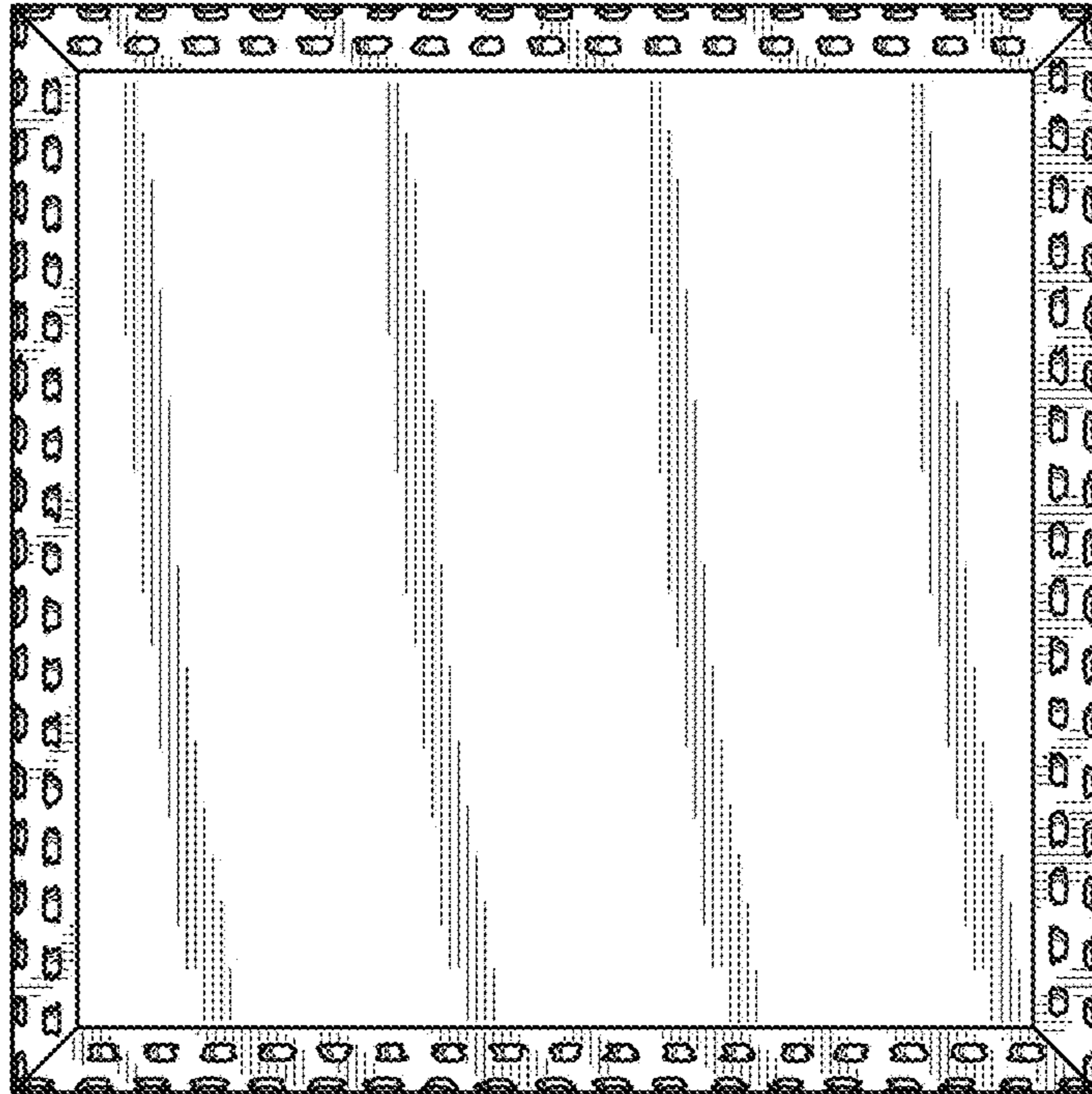


FIG. 4

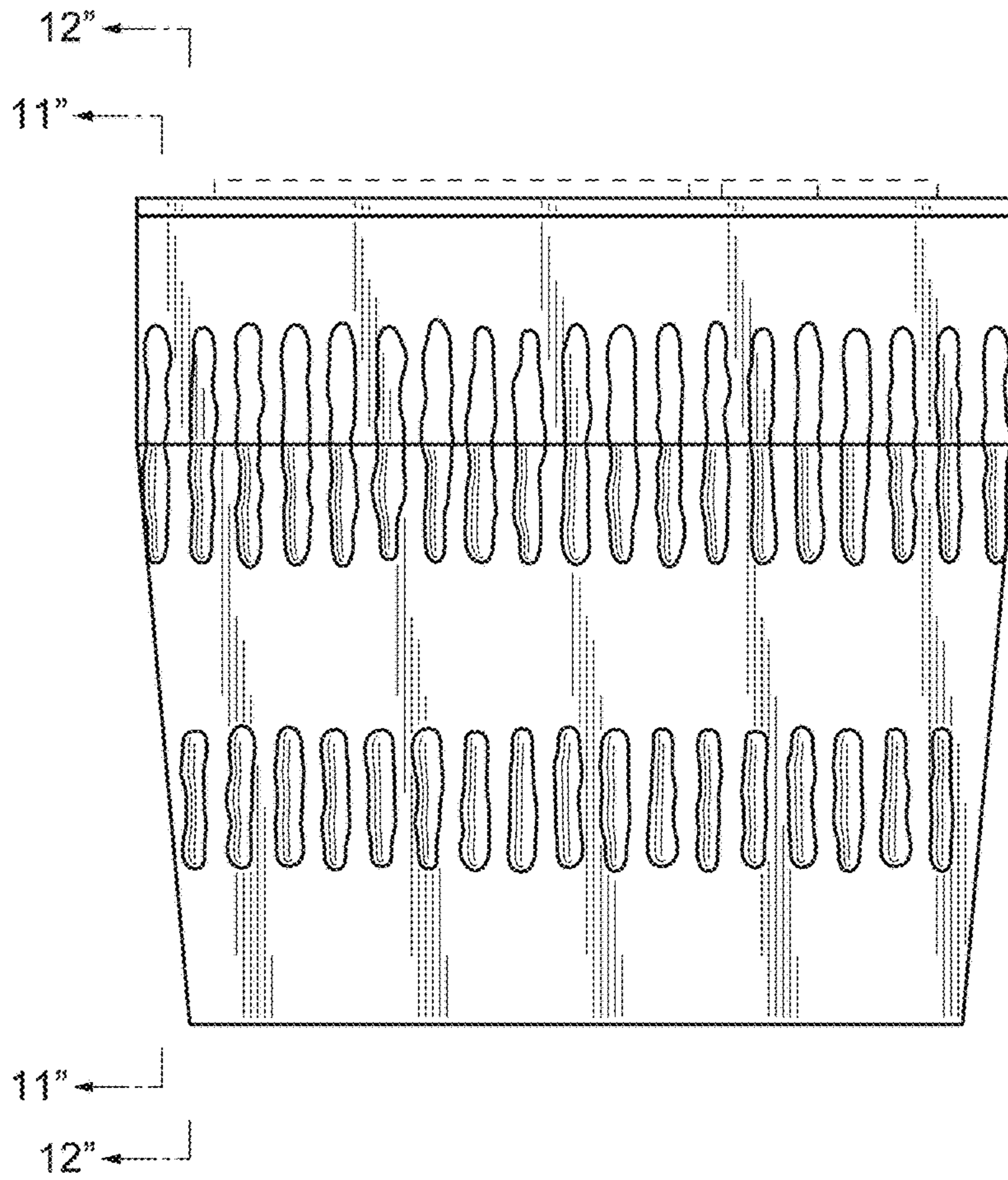


FIG. 5

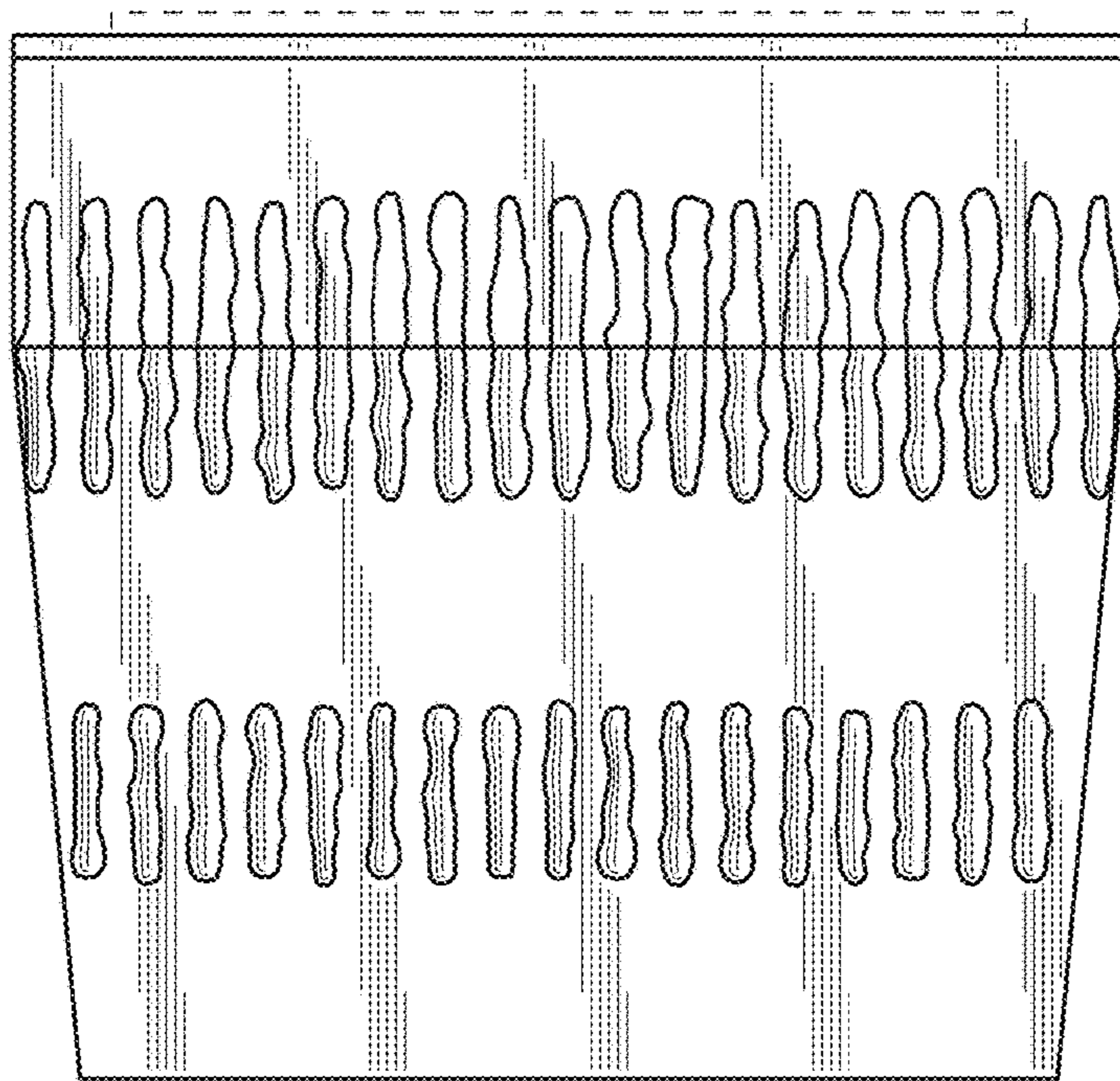


FIG. 6



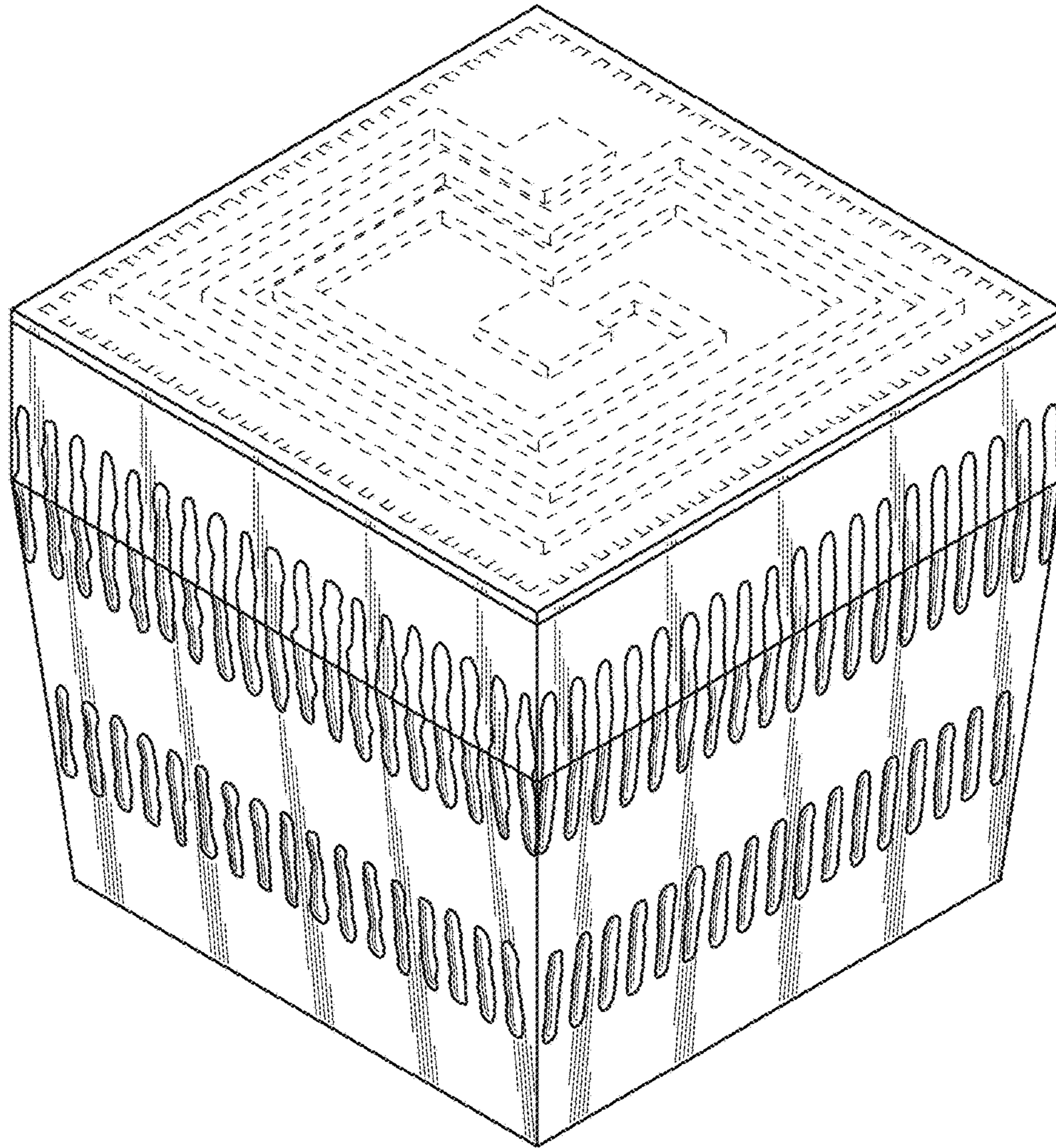


FIG. 7

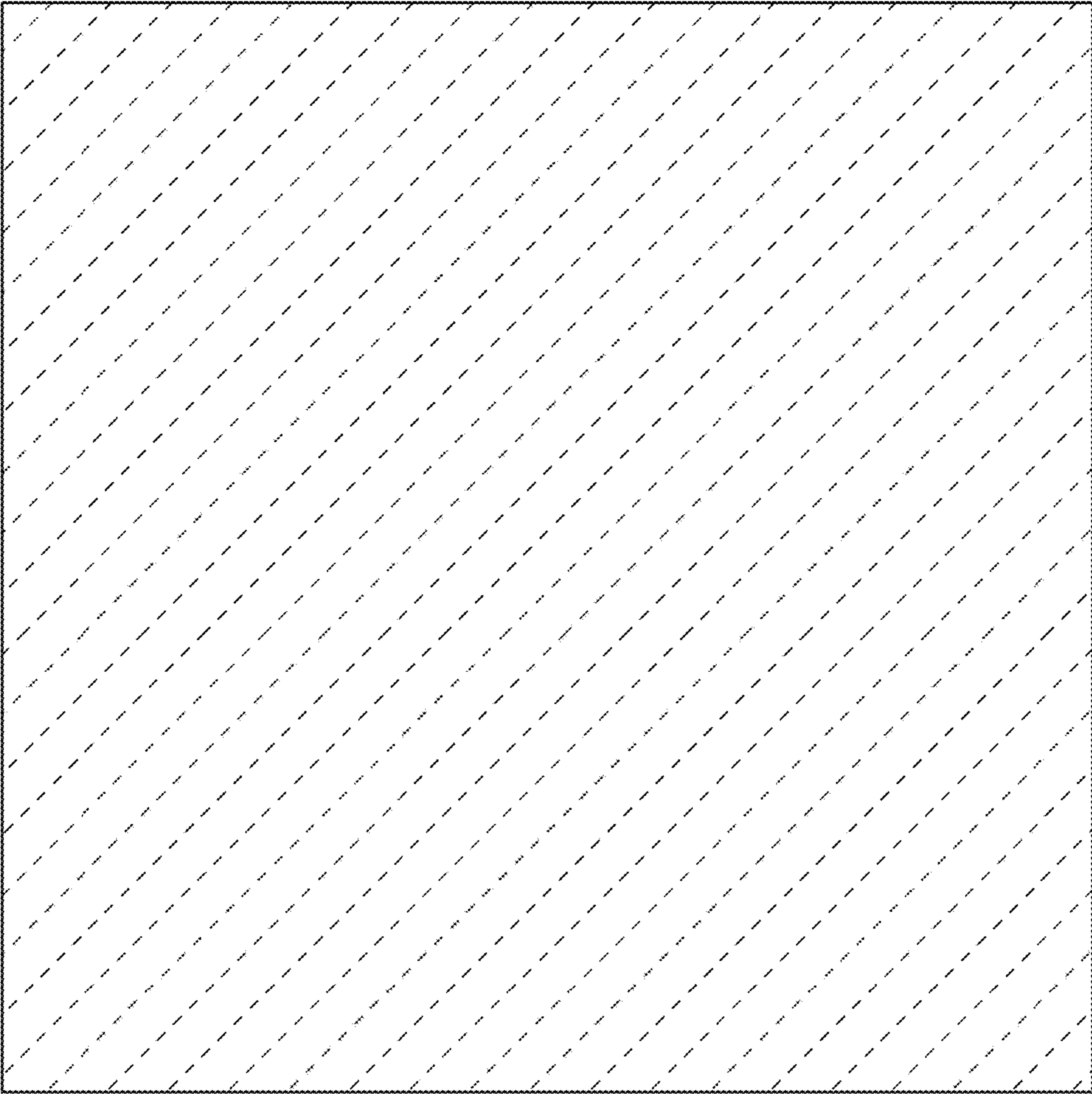


FIG. 8

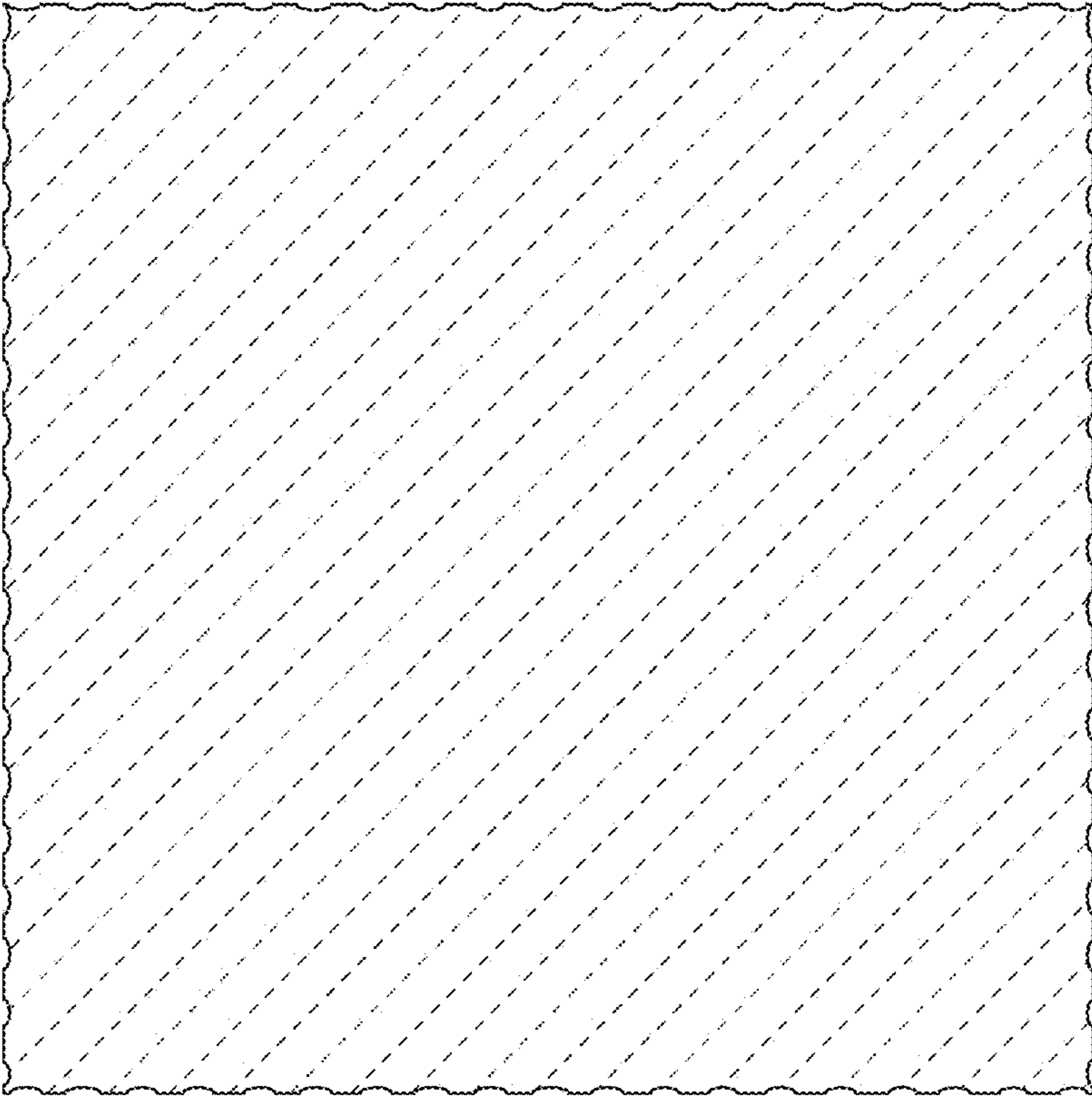


FIG. 9

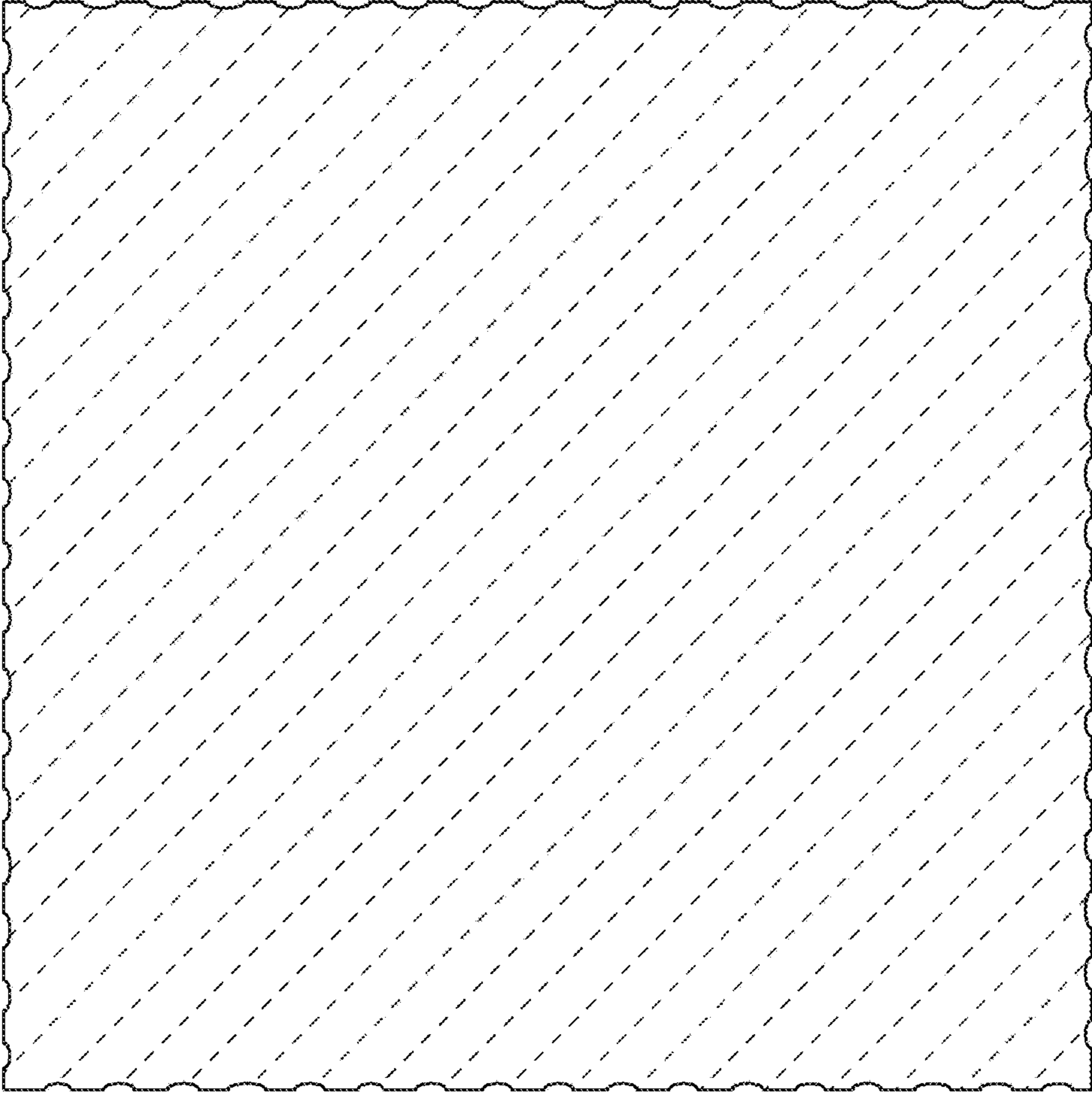


FIG. 10



FIG. 11



FIG. 12